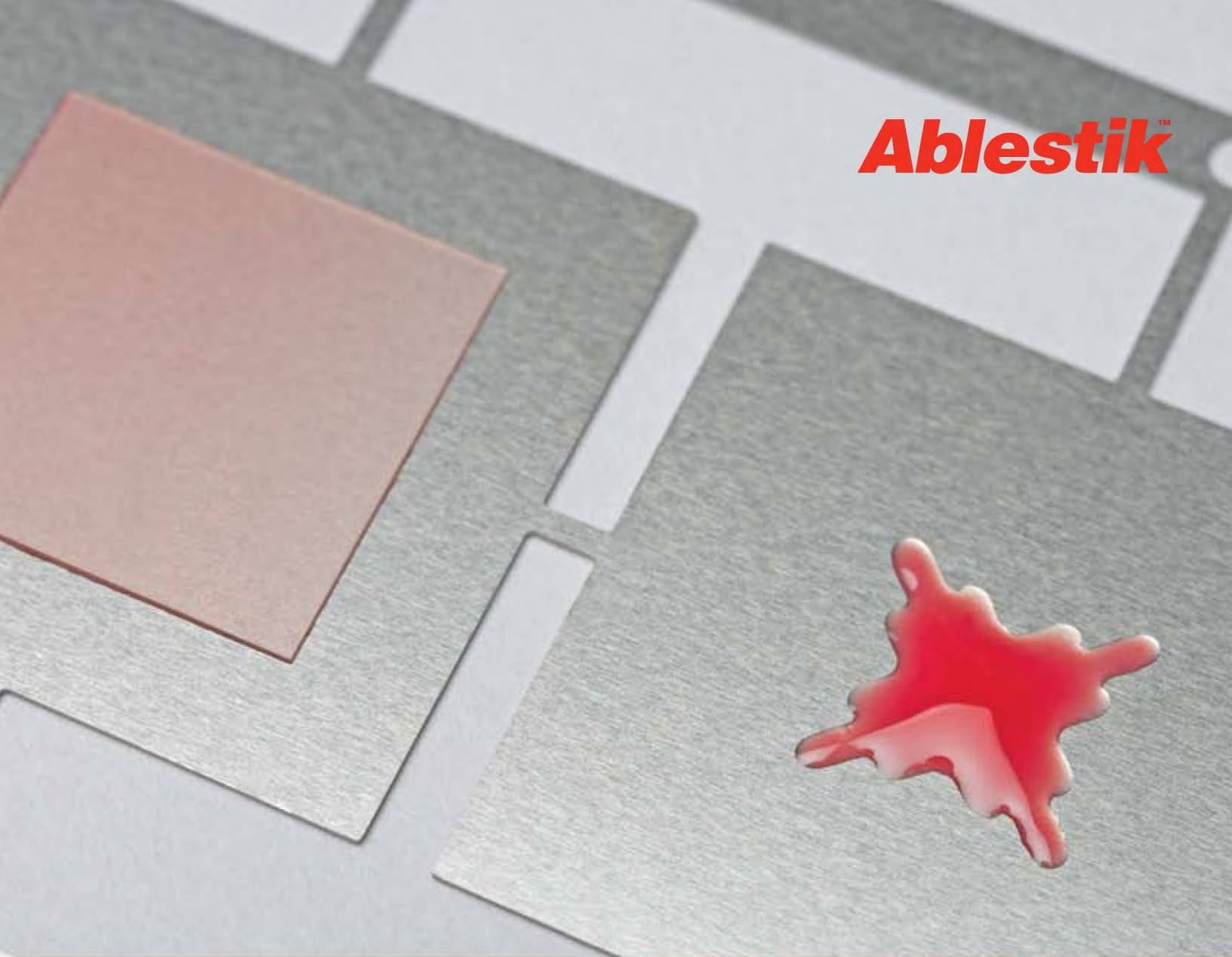




Ablestik™



Self-Filleting® Applications *Alternative to Die Attach Films*



Henkel



Self-Filleting® Die Attach from Henkel: Technology so Advanced it Does the Work for You

Conventional die attach pastes require the utmost precision for material dispensing techniques, as well as for die placement. One wrong move and yield may suffer. But Henkel's breakthrough Ablestik® Self-Filleting® die attach material ends the guesswork and delivers a material that offers exceptionally uniform bondline thickness control and eliminates the need for difficult, complex dispense patterns. With Ablestik® Self-Filleting® pastes, a simple pattern of material is dispensed, capillary forces draw the material to the edge of the die pad, and a fillet is formed. Die placement pressure can be significantly reduced, bondline thickness tightly controlled, and yields dramatically improved. Advanced die attach materials so smart they know where to go.



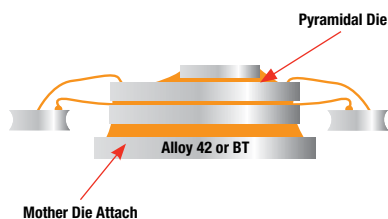
It's a Paste that Acts Like a Film!

Self-Filleting® can potentially be a viable solution for any controlled flow application that would normally require film due to tight tolerances.

What is Ablestik® Self-Filleting® Adhesive?

Ablestik® Self-Filleting® adhesive is a dispensable paste that flows under minimal bond force and stops flowing when it contacts the edge of the die. The Ablestik® Self-Filleting® process has been demonstrated successfully on:

- Die to Substrate
- Pyramidal Die stack

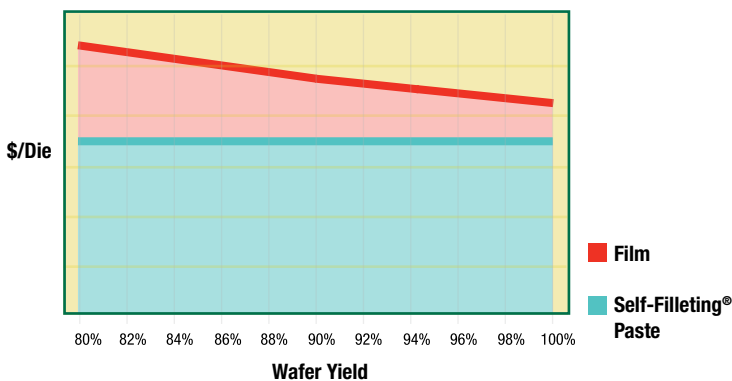


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Ablestik® Self-Filleting® Product Offering

	3900	AAA3300	AAA3320	RP869
Application	TSOP Alloy 42	Die to Substrate Pyramidal	Pyramidal Die Stack	Die to Substrate Pyramidal
Viscosity, cPs	8,000	12,000	13,000	5,600
Thixo	2.5	<3.0	<2.1	2.7
RT Modulus, MPa	280	25	3740	2910
Tg, °C	-20	-27	82	2
CTE α_1/α_2, ppm/°C	90/212	72/173	45/117	59/159
Reliability	MSL 2/260°C	MSL 2/260°C	MSL 2/260°C	MSL 2/260°C
Work Life	24 hours	24 hours	24 hours	24 hours

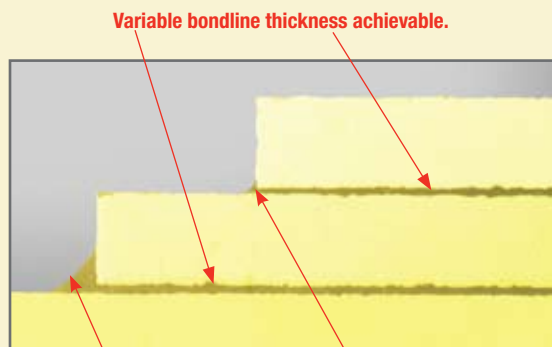
Alternative to Film



Process Advantages

- No bulky fillers to cause die damage
- Comparable to film in tight tolerance applications
- Improved wetting vs. film
- Standard dispense processing

Ablestik® Self-Filleting® adhesive flows under minimal bond force and stops flowing when it contacts the edge of the die.



Self-Filleting® process shows minimal to no fillet. No chance of contamination on the die top.

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